

Initial Product/Process Change Notification Document #:IPCN25425X

Issue Date:13 Dec 2023

Title of Change:		Assembly material change of 1.0mil gold wire to 1.0mil palladium coated copper for SSOT6 Analog package in onsemi Cebu, Philippines.		
Proposed First Ship date:	29 Apr 2024 or earlier	29 Apr 2024 or earlier if approved by customer		
Contact Information:		Contact your local onsemi Sales Office or Ernesto.Villamor@onsemi.com or Joseph.Mendoza@onsemi.com		
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Type of Notification:	advance notification al change details and dev The completed qualific Product/Process Chang Product/Process Chang	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >		
Marking of Parts/ Traceability of Change:	Identification through	Identification through date code cut off.		
Change Category:	Assembly Change	Assembly Change		
Change Sub-Category(s):	Material Change	Material Change		
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Cebu, Philippines		None		

Description and Purpose:

- Material changes from Au Palladium Coated Copper (PCC) wire.
- Standardization of bonding wire use in SSOT6 analog package.

	From	То	
Bond Wire	1.0 mil Au wire	1.0 mil PCC wire	

There is no product marking change as a result of this change.

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Qualification Plan:

QV DEVICE NAME: FAN5622SX

RMS: F91436

PACKAGE: F369 | TSOT-23 6L AU SNGL HPBF

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
Temperature Cycling	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: November 3, 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

Part Number	Qualification Vehicle
FAN5622SX	FAN5622SX

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